## AMENDMENTS TO THE CLAIMS

**This listing of claims will replace all prior versions and listings of claims in the application:**

## LISTING OF CLAIMS:

1. (original): An inorganic powder having a frequency-size distribution with multiple peaks, wherein the peaks are present at least in the particle size regions from 0.2 to 2 μm and from 2 to 63 μm

wherein the maximum particle size is 63 μm or less, the average particle size is from 4 to 30 μm, and the mode size is from 2 to 35 μm

wherein the percentage of particles having a particle size of less than 2 μm is from 0 to 20 mass% and the mode size of particles having a particle size of less than 2 μm is from 0.25 to 1.5 μm

wherein the percentage of particles having a particle size of 8 μm or more is from 65 to 90 mass%

wherein the percentage of particles having a particle size of from 2 to 8 μm is from 0 to 15 mass%.

2. to 6. (canceled).

7. (original): The inorganic powder as claimed in claim 1, wherein the spheroidicity is from 0.68 to 0.95 and the spheroidization ratio is from 0.63 to 0.95.

8. (original): The inorganic powder as claimed in claim 1, wherein the spheroidicity of particles having a particle size of less than 2 μm is from 0.5 to 0.95 and the spheroidization ratio thereof is from 0 to 0.9.

9. (original): The inorganic powder as claimed in claim 1, wherein the spheroidicity of particles having a particle size of 8 μm or more is from 0.7 to 0.95 and the spheroidization ratio thereof is from 0.7 to 0.95.

10. (original): The inorganic powder as claimed in claim 1, wherein the thermal conductivity of the inorganic powder in the single crystal state is 30 W/m·K or more.

11. (previously presented): The inorganic powder as claimed in claim 1, which is an alumina powder.

12. (original): The inorganic powder as claimed in claim 11, wherein the α alumina crystal phase fraction of the alumina powder is from 30 to 75 mass%.

13. (original): The inorganic powder as claimed in claim 11, wherein the α alumina crystal phase fraction of the particle of less than 2 μm is from 90 to 100 mass%.

14. (original): The inorganic powder as claimed in claim 11, wherein the α alumina crystal phase fraction of the particle of 8 μm or more is from 30 to 70 mass%.

15. (original): The inorganic powder as claimed in claim 1, wherein the content of metal aluminum is 0.05 mass% or less.

16. (original): The inorganic powder as claimed in claim 1, wherein the content of sulfate ion is 15 ppm or less.

17. (original): The inorganic powder as claimed in claim 1, wherein the content of chlorine ion is 15 ppm or less.

18. (original): The inorganic powder as claimed in claim 1, wherein the content of $Fe_2O_3$ is 0.03 mass% or less.

19. (original): The inorganic powder as claimed in claim 1, which contains substantially no particles of less than 50 nm.

20. (original): The inorganic powder as claimed in claim 1, which is subjected to surface-hydrophobing treatment with at least one surface-treating agent selected from silane-based coupling agent and titanate-based coupling agent.

21. (previously presented): A resin composition filled with the inorganic powder described in claim 1.

22. (original): The resin composition as claimed in claim 21, wherein from 50 to 90 mass% of the inorganic powder is filled.

23. (previously presented): The resin composition as claimed in claim 21, wherein when the resin composition is formed into a thin-film insulating resin composition with a thickness of 40 to 90 μm, the dielectric breakdown strength as measured by a dielectric breakdown voltage test prescribed in JIS C2110 is 39 kV/mm or more.

24. (previously presented): A circuit board for mounting on automobiles, using the resin composition described in claim 21.

25. (previously presented): A circuit board for mounting on electronic devices, using the resin composition described in claim 21.

26. (previously presented): A high thermally conductive member for installation in electronic devices, using the resin composition described in claim 21.

27. (previously presented): A high thermally conductive member for electronic components, using the resin composition described in claim 21.

28. (previously presented): The high thermally conductive member as claimed in claim 26, which is in a sheet form.

29. (previously presented): The high thermally conductive member as claimed in claim 26, which is in a form of gel or paste.

30. (previously presented): The high thermally conductive member as claimed in claim 26, which is underfill-agent type member.

31. (previously presented): The high thermally conductive member as claimed in claim 26, which is applied by coating onto a heating portion of an elemental device.

32. (previously presented): A metal-based circuit board, a metal core-type circuit board and a structure body thereof, wherein the resin composition described in claim 21 is used as a high thermally conductive member serving also as an insulating adhesive layer or the like.

33. (previously presented): A structure body of a high thermally conductive metal member-integrated electronic component, wherein a heat generating electronic component and a high thermally conductive metal member are bonded by using the high thermally conductive member described in claim 26.

34. (previously presented): An LED circuit board using the high thermally conductive member described in claim 26.

35. (previously presented): An automobile using the circuit board claimed in claim 32.

36. (previously presented): An electronic product using the circuit board claimed in claim 32.

37. (previously presented): A light indicator using the circuit board claimed in claim 32.

38. (previously presented): A display device using the circuit board claimed in claim 32.